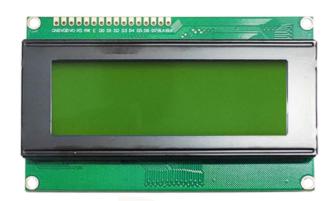
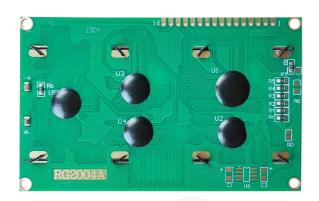


## **RG2004**

## **DISPLAY 20×4 GREEN**





### 1. Features:

The features of LCD are as follows:

• Display mode : STN /GREEN, NEGATIVE, TRANSMISSIVE

• Colour : Display dot :BLACK

Background: GREEN

• Display Format : 20 (characters) × 4 (line)

• \* IC : 7066 7065

• Interface Input Data : 8 Bits

• Driving Method : 1/16 Duty, 1/5 Bias

• Viewing Direction: 6 O'clock

• Backlight : LED (WHITE)

## 2. Mechanical Specifications:

| Unit |
|------|
| mm   |
| mm   |
| mm   |
| -    |
| mm   |
| mm   |
| _    |



# 3. Electrical Specifications:

### 1. Absolute Maximum Ratings (Vss = 0V)

| Item                         | Symbol      | Sta           | Unit      |                |        |
|------------------------------|-------------|---------------|-----------|----------------|--------|
| Rem                          | Cymbol      | Min.          | Тур.      | Max.           | Offic  |
| Supply Voltage For Logic     | Vdd         | -0.3          | -         | 5.0            | V      |
| Supply Voltage For LCD Drive | Vo,<br>Vout | -0.3          | -         | 14.5           | V      |
| Operating Temp.              | Тор         | -20           | -         | +70            | °C     |
| Storage Temp.                | Тѕт         | -30           | -         | +80            | °C     |
| Static Electricity           | Be s        | sure that you | are grour | nd when handir | ng LCM |

### 2. Electrical Characteristics:

| Item           |           | Symbol          | Test<br>Condition         | Min.   | Тур. | Max.   | Unit     |
|----------------|-----------|-----------------|---------------------------|--------|------|--------|----------|
| Supply Voltage | For Logic | VDD – VSS       | Ta=25℃                    | 4.8    | 5.0  | 5.2    | <b>V</b> |
| Supply Voltage | e For LCD | VDD — Vo        | <b>Ta=25</b> ℃            | 4.0    | 4.2  | 4.4    | ٧        |
|                | "H" Level | V <sub>IH</sub> | Ta=25°C                   | 0.8VDD | -    | Vdd    | V        |
| Input Voltage  | "L" Level | V <sub>IL</sub> | 14-25 C                   | Vss    | -    | 0.2VDD | V        |
| Output Voltage | "H" Level | V он            | I <sub>ОUT</sub> = -0.5mA | 0.8VDD | -    | VDD    | V        |
| Output Voltage | "L" Level | V <sub>OL</sub> | I <sub>OUT</sub> = 0.5mA  | Vss    | ı    | 0.2VDD | V        |
| Current Cons   | umption   | I <sub>DD</sub> | $V_{IN} = V_{DD}$         | -      | -    | 1.0    | mA       |

NOTE: 1) Duty ratio=1/65, Bias=1/9

2) Measured in Dots ON-state



#### 3. BACKLIGHT:

### **3.1** Absolute Maximum Ratings:

| Item              | Symbol | Condition | Min. | Тур. | Max | Unit |
|-------------------|--------|-----------|------|------|-----|------|
| Forward Current   | IF     | Ta= 25℃   | -    | -    | 20  | mA   |
| Reverse Voltage   | VR     | 1a=23 C   | -    | -    | 5   | V    |
| Power Dissipation | PD     | Ta= 25°C  | -    | -    | 100 | mW   |

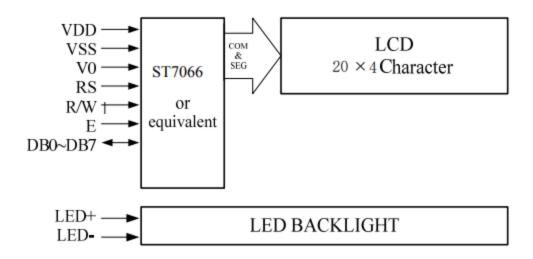
## **3.2** Opto-electronic Characteristics:

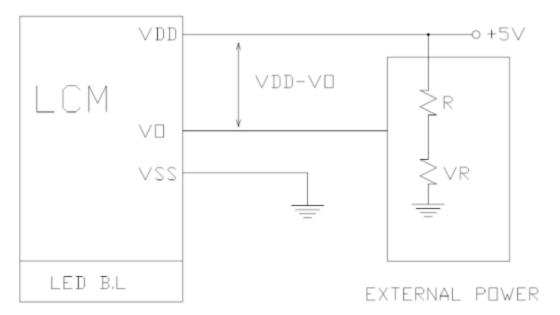
| Item            | Symbol | Condition | Min. | Тур. | Max | Unit  |
|-----------------|--------|-----------|------|------|-----|-------|
| Forward Voltage | VF     | Ta= 25℃   | 4.8  | 5.0  | 5.2 | V     |
| Luminous        | -      | IF= 32mA  | 100  | 150  | -   | cd/m² |

<sup>\*</sup> The brightness is measured without LCD panel



## 4. Schematic Design:





VDD-V0:LCD DRIVING V0LTAGE VR: 10K ~ 20K IF V0P(LCD) > 5.0V,THE EXERNAL POWER MUST BE USED



## **5. Interface Pin Function:**

| Pin No. | Pin Out | Description   |
|---------|---------|---|
| 1       | VSS     | GND   |
| 2       | VDD     | Logic supply voltage (5.0V)   |
| 3       | vo      | Power supply for LCD  |
| 4       | RS      | Data/Instruction RS=high: Indicates that data of DB0~DB7 is display data. RS=low: Indicates that data of DB0~DB7 is instruction     |
| 5       | R/W     | Read/Write R/W=high: Data of DB0~DB7 can be read by CPU. R/W=low: Data of DB0~DB7 can be written into LCD driver IC                 |
| 6       | E       | Enable When write(R/W=low): Data of DB0~DB7 is latched at the fall of E When read(R/W=high): Data is read while E is at high level. |
| 7       | DB0     |   |
| 8       | DB1     |   |
| 9       | DB2     |   |
| 10      | DB3     | Data Bus line.  |
| 11      | DB4     |   |
| 12      | DB5     |   |
| 13      | DB6     |   |
| 14      | DB7     |   |
| 15      | A       | LED Backlight +.  |
| 16      | K       | LED Backlight   |



### 6. Command List:

#### Instruction Table:

| instruction rat                  |    |     |     | Inst | ructi | on ( | Code | )   |     |     |  | Description      |
|----------------------------------|----|-----|-----|------|-------|------|------|-----|-----|-----|--|------------------|
| Instruction                      | RS | R/W | DB7 | DB6  | DB5   | DB4  | DB3  | DB2 | DB1 | DB0 | Description  | Time<br>(270KHz) |
| Clear<br>Display                 | 0  | 0   | 0   | 0    | 0     | 0    | 0    | 0   | 0   | 1   | Write "20H" to DDRAM. and<br>set DDRAM address to<br>"00H" from AC   | 1.52 ms          |
| Return<br>Home                   | 0  | 0   | 0   | 0    | 0     | 0    | 0    | 0   | 1   | x   | Set DDRAM address to<br>"00H" from AC and return<br>cursor to its original position<br>if shifted. The contents of<br>DDRAM are not changed. | 1.52 ms          |
| Entry Mode<br>Set                | 0  | 0   | 0   | 0    | 0     | 0    | 0    | 1   | I/D | s   | Sets cursor move direction<br>and specifies display shift.<br>These operations are<br>performed during data write<br>and read.               | 37 us            |
| Display<br>ON/OFF                | 0  | 0   | 0   | 0    | 0     | 0    | 1    | D   | С   | В   | D=1:entire display on<br>C=1:cursor on<br>B=1:cursor position on   | 37 us            |
| Cursor or<br>Display<br>Shift    | 0  | 0   | 0   | 0    | 0     | 1    | S/C  | R/L | x   | x   | Set cursor moving and<br>display shift control bit, and<br>the direction, without<br>changing DDRAM data.                                    | 37 us            |
| Function<br>Set                  | 0  | 0   | 0   | 0    | 1     | DL   | N    | F   | x   | х   | DL:interface data is 8/4 bits<br>N:number of line is 2/1<br>F:font size is 5x11/5x8  | 37 us            |
| Set CGRAM<br>address             | 0  | 0   | 0   | 1    | AC5   | AC4  | AC3  | AC2 | AC1 | AC0 | Set CGRAM address in<br>address counter  | 37 us            |
| Set DDRAM<br>address             | 0  | 0   | 1   | AC6  | AC5   | AC4  | AC3  | AC2 | AC1 | AC0 | Set DDRAM address in<br>address counter  | 37 us            |
| Read Busy<br>flag and<br>address | 0  | 1   | BF  | AC6  | AC5   | AC4  | AC3  | AC2 | AC1 | AC0 | Whether during internal<br>operation or not can be<br>known by reading BF. The<br>contents of address counter<br>can also be read.           | 0 us             |
| Write data to RAM                | 1  | 0   | D7  | D6   | D5    | D4   | D3   | D2  | D1  | D0  | Write data into internal<br>RAM<br>(DDRAWCGRAM)  | 37 us            |
| Read data from RAM               | 1  | 1   | D7  | D6   | D5    | D4   | D3   | D2  | D1  | D0  | Read data from internal<br>RAM<br>(DDRAWCGRAM)   | 37 us            |

#### Note:

Be sure the ST7066U is not in the busy state (BF = 0) before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Instruction Table for the list of each instruction execution time.



# 7. Timing Characteristics (Continued):

### AC Characteristeics (VDD = $2.7 \text{ V} \sim 4.5 \text{ V}$ , Ta = $-30 \sim +85 ^{\circ}\text{C}$ )

| Mode             | Characteristeics               | Symbol | Min   | Тур | Max  | Unit |
|------------------|--------------------------------|--------|-------|-----|------|------|
|                  | Clock Pulse Width (Hight, Low) | Tc     | 500   | -   | -    |      |
| Interface Mode   | Clock Rise / Fall Time         | Tr,Tf  | -     | -   | 20   |      |
| With             | Clock Setup Time               | Tsu1   | 500   | -   | -    |      |
| Extension Driver | Data Setup Time                | Tsu2   | 300   | -   | -    | ns   |
| (Refer to Fig-8) | Data Hold Time                 | Tdh    | 300   | -   | -    |      |
|                  | M Delay Time                   | TDM    | -1000 | -   | 1000 |      |

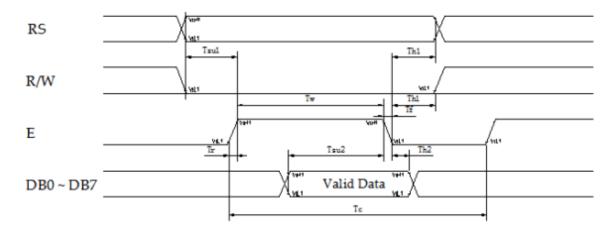


Figure 6. Write Mode Timing Diagram



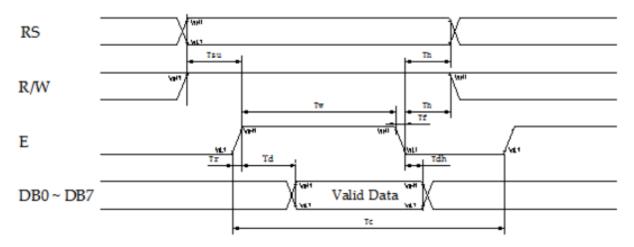


Figure 7. Read Mode Timing Diagram

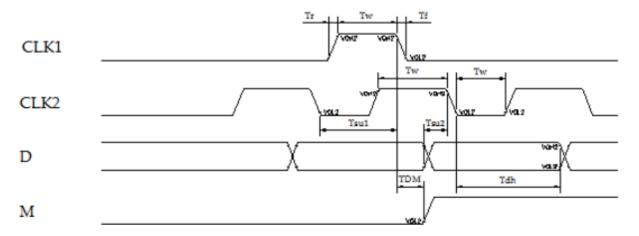


Figure 8. Interface Mode With Extension Driver Timing Diagram



## **8.** Quality Specification (Continued):

### 8-3. Sampling Plan and Acceptance

### 1. Sampling Plan

MIL - STD - 105E (  $\blacksquare$  ) ordinary single inspection is used.

### 2. Acceptance

Major defect: AQL = 0.25%Minor defect: AQL = 0.65%

#### 8-4. Criteria

#### a) COB

| Defect | Inspection Item   | Inspection Standards   |        |
|--------|---|--|--------|
| Major  | PCB copper flakes peeling off                           | Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup> | Reject |
| Major  | Height of coating epoxy Exceed the dimension of drawing |  | Reject |
| Major  | Void or hole of coating epoxy Expose bonding wire or IC |  | Reject |
| Major  | PCB cutting defect                                      | Exceed the dimension of drawing  | Reject |

### b) SMT

| Defect | Inspection Item   | Inspection Standa                  | ards             |
|--------|---|------------------------------------|------------------|
| Minor  | Component marking not readable  |                                    | Reject           |
| Minor  | Component height  | Exceed the dimension<br>Of drawing | Reject           |
| Major  | Component solder defect (missing, extra, wrong component or wrong orientation |                                    | Reject           |
| Minor  | Component position shift  | X < 3/4Z<br>Y > 1/3D               | Reject<br>Reject |
| Minor  | component  soldering pad  Component tilt                                      | Y > 1/3D                           | Reject           |



| Minor | Insufficient solder  component PAD | θ ≤ 20' | Reject |
|-------|------------------------------------|---------|--------|
|       | PCB                                |         |        |

## c) Metal (Plastic) Frame

| Defect | Inspection Item          |   | Inspection S        | Standards                    |  |  |  |
|--------|--------------------------|---|---------------------|------------------------------|--|--|--|
| Major  | Crack / breakage         | Anywher   | Reject              |                              |  |  |  |
| •      |                          | W   | L                   | Acceptable of Scratch        |  |  |  |
|        |                          | w<0.03mm  | Any                 | Ignore                       |  |  |  |
|        |                          | 0.03mm <u>&lt;</u> w<0.05mm   | L <u>&lt;</u> 5.0mm | 2                            |  |  |  |
| Minor  | Frame Scratch            | 0.05mm <w<0.1mm< td=""><td>L&lt;3.0mm</td><td>1</td></w<0.1mm<>   | L<3.0mm             | 1                            |  |  |  |
|        |                          | w>0.1mm   | Any                 | 0                            |  |  |  |
|        |                          | Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm.  2. Scratch on the back side of frame (not visible) can be ignored.             |                     |                              |  |  |  |
|        |                          |   |                     | Acceptable of Dents / Pricks |  |  |  |
|        |                          | Φ <u>&lt;</u> 1.0mr   | n                   | 2                            |  |  |  |
|        |                          | 1.0<⊕ <u>&lt;</u> 1.5   | mm                  | 1                            |  |  |  |
| Minor  | Frame Dent, Prick        | 1.5mm>  | 1.5mm>⊕             |                              |  |  |  |
|        | $\Phi = \frac{L + W}{2}$ | Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm  2. Dent / prick on the back side of frame (not visible) can be ignored |                     |                              |  |  |  |
| Minor  | Frame Deformation        | Exceed the dimension of drawing   |                     |                              |  |  |  |
| Minor  | Metal Frame Oxidation    |   | Any rust            |                              |  |  |  |

### d) Flexible Film Connector (FFC)

| Defect                        | In                        | spection Item  | Inspection Standards       |            |  |  |
|-------------------------------|---------------------------|----------------|----------------------------|------------|--|--|
| Minor                         | Tilted soldering          |                | Within the angle ±3°       | Acceptable |  |  |
| Minor                         | Uneven solder joint /bump |                |                            | Reject     |  |  |
| Hole $\Phi = \frac{L + W}{L}$ |                           | $\Phi = L + M$ | Expose the conductive line | Reject     |  |  |
| Minor                         | i ioie                    | 2              | Φ > 1.0mm                  | Reject     |  |  |
| Minor                         | Po                        | sition shift   | Y > 1/3D                   | Reject     |  |  |
| IVIIIIOI                      | ·                         |                | X > 1/2Z                   | Reject     |  |  |

#### e) Screw

| Defect Inspection Item |                      | Inspection Standards             |        |  |  |
|------------------------|----------------------|----------------------------------|--------|--|--|
| Major                  | Screw missing/loosen |                                  | Reject |  |  |
| Minor                  | Screw oxidation      | Any rust                         | Reject |  |  |
| Minor                  | Screw deformation    | Difficult to accept screw driver | Reject |  |  |

## f) Heat seal 、TCP 、FPC

| Defect   | Inspection Item                         | Inspection Standards        |        |  |
|----------|---|-----------------------------|--------|--|
| Major    | Scratch expose conductive layer         |                             | Reject |  |
| Minor    | HS Hole $\Phi = \frac{L + W}{2}$        | Φ > 0 <mark>.2mm</mark>     | Reject |  |
| Major    | Adhesion strength                       | Less than the specification | Reject |  |
| Minor    | Position shift                          | Y > 1/3D                    | Reject |  |
| IVIIIIOI | - \ \ - \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | X > 1/2Z                    | Reject |  |
| Major    | Conductive line break                   |                             | Reject |  |



## g) LED Backing Protective Film and Others

| Defect | Inspection Item      | Inspection Standards   |        |  |  |
|--------|----------------------|--|--------|--|--|
|        |                      | Acceptable number of units   |        |  |  |
|        |                      | Ф <u>&lt;</u> 0.10mm   | Ignore |  |  |
|        |                      | 0.10<⊕ <u>&lt;</u> 0.15mm  | 2      |  |  |
| Minor  | LED dirty, prick     | 0.15<⊅ <u>&lt;</u> 0.2mm   | 1      |  |  |
|        |                      | Ф>0.2mm  | 0      |  |  |
|        |                      | The distance between any two spots should be ≥10mmAr spot/dot/void outside of viewing area is acceptable |        |  |  |
| Minor  | Protective film tilt | t Not fully cover LCD F  |        |  |  |
| Major  | COG coating          | Not fully cover ITO circuit  | Reject |  |  |

## h) Electric Inspection

| Defect Inspection Item |       | Inspection Standards |        |
|------------------------|-------|----------------------|--------|
| Major                  | Short |                      | Reject |
| Major                  | Open  |                      | Reject |



## i) Inspection Specification of LCD

| Defect  |  | Inspect Item  | Inspection Standards |   |   |  |                 |                     |                |         |
|---------|--|---|----------------------|---|---|--|-----------------|---------------------|----------------|---------|
|         |  | * Glass Scratch   | W                    | W<0.03  |   | 0.03 <w<0.05< td=""><td>W&gt;0.05</td></w<0.05<> |                 | W>0.05              |                |         |
|         |  |   | ACC.                 |   | L<  | 5  | <u> </u>        | .<3                 |                | Any     |
| Minor   | Linear Defect                            | * Polarizer Scratch   | NO.                  |   | 1   |  |                 | 1                   |                | Reject  |
|         |  | * Fiber and Linear material   | Note                 | L is th   | L is the length and V   |  | is the          | width of th         | e def          | ect     |
|         |  | * Foreign material  | Ф                    | Φ <b>&lt;</b> 0.1 0.1<Φ <b>&lt;</b> 0.15 0.15<Φ <b>&lt;</b> 0.2                       |   |  | <u>&lt;</u> 0.2 | Ф>0.2               |                |         |
|         | Black Spot and                           | between glass and polarizer or glass  | ACC.<br>NO.          | 3EA   | /1PC  | 2  |                 | 1                   |                | 0       |
| Minor   | Polarizer<br>Pricked                     | and glass  * Polarizer hole or protuberance by external force                                   | Note                 | $\Phi \;$ is the average diameter of the defect. Distance between two defects > 10mm. |   |  |                 |                     | stance between |         |
|         |  | * Unobvious   | Ф                    | Φ<  | :0.1  | 0.1<⊕ <u>&lt;</u>                                | 0.15            | 0.15<Φ <sub>5</sub> | ≤0.2           | Ф>0.2   |
|         |  | transparent foreign material between  | ACC.<br>NO.          | 3EA   | 1PC   | 2  |                 | 1                   |                | 0       |
| Minor   | White Spot and<br>Bubble in<br>polarizer | glass and glass or<br>glass and polarizer  * Air protuberance<br>between polarizer<br>and glass | Note                 |   | Φ is the average diameter of the defect. Distance between two defects > 10mm. |  |                 |                     | stance between |         |
|         |  |   | Ф                    | Φ <u>&lt;</u>   | 0.10 0.10<⊕ <u>&lt;</u> 0.20  |  |                 |                     | ⊕>0.2          |         |
|         | Segment<br>Defect                        | w v   | ACC.<br>NO.          | 3EA/1PC 2   |   |  | 0               |                     |                |         |
| Minor   |  | W   |                      | W is more than 1/2 segment width Reje   |   |  | Reject          |                     |                |         |
| WIIITOT |  |   | Note                 | $\Phi = \frac{-L + W}{2}$ Distance between two defect is 10mm                         |   |  |                 |                     |                |         |
|         |  |   | Φ                    | Ф   | <u>&lt;</u> 0.10  |  | 0.10            | <⊕ <u>&lt;</u> 0.20 |                | Ф>0.2   |
|         | Protuberant<br>Segment                   |   | W                    |   | Glue  | W <u>&lt;</u> 1/2 Seg , W <u>&lt;</u> 0.2        |                 | Ignore              |                |         |
| Minor   |  | $\Phi = (L + W)/2$  | ACC.<br>NO.          | 3EA/1PC 2   |   |  | 0               |                     |                |         |
|         |  | Ψ = (L+W)/2   |                      | 1. Segment  |   |  |                 | l                   |                |         |
|         |  |   | В                    | 3 B <u>&lt;</u> 0   |   |  |                 | B <u>&lt;</u> 1.0mm |                | B>1.0mm |
|         |  | B A   | B-A                  | A B-A<  |   | :1/2B B-A<0.2                                    |                 | A<0.2               | B-A<0.25       |         |
| Minor   | Assembly Mis-                            |   | Judg                 | ge Acceptable Acceptable  |   |  |                 | Acceptable          |                |         |
|         | alignment                                | 0.35mm  | 2. Dot Matrix        |   |   |  |                 |                     |                |         |
|         |  |   |                      |   |   |  |                 | Reject              |                |         |



| Minor | Stain on LCD<br>Panel Surface |  | Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the aboveitems: "Black spot" and "White Spot" |
|-------|-------------------------------|--|--|
|-------|-------------------------------|--|--|

## 9. Reliability:

| NO. | Item                       | Condition   | Criterion  |  |
|-----|----------------------------|---|--|--|
| 1   | High Temperature Operating | 70°C, 96Hrs   |  |  |
| 2   | Low Temperature Operating  | -20℃, 96Hrs   |  |  |
| 3   | High Humidity              | 40℃, 90%RH, 96Hrs   | (R)  |  |
| 4   | High Temperature Storage   | 80℃, 96Hrs  | No defect in cosmetic  |  |
| 5   | Low Temperature Storage    | - <mark>30℃, 96Hrs</mark>   | and operational function allowable.  |  |
| 6   | Vibration                  | Random wave  10 ~ 100Hz  Acceleration: 2g  2 Hrs per direction(X,Y,Z)                                   | Total current Consumption should be below double of initial value.                             |  |
| 7   | Thermal Shock              | -10℃ to 25℃ to 60℃<br>(60Min) (5Min) (60Min)<br>16Cycles  |  |  |
| 8   | ESD Testing                | Contract Discharge Voltage:<br>+1 ~ 5kV and -1 ~ -5kV  Air Discharge Voltage:<br>+1 ~ 8kV and -1 ~ -8kV | There will be discharged ten times at every discharging voltage cycle. The voltage gap is 1kV. |  |

*Note:* 1) Above conditions are suitable for xinnuoya standard products.

2) For restrict products, the test conditions listed as above must be revised.



## 10. Handling Precaution:

#### (1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizerswhich easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommendedbelow) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before poweris turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
- Modules use LCD elements, and must be treated as such. Avoid intense shockand falls from a height.
- To prevent modules from degradation. Do not operate or store them exposeddirectly to sunshine or high temperature/humidity.
- (5) Caution for operation
- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.



## **Handling Precaution (Continued):**

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show darkcolor in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 60°C, 90% RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance, for years) for thepurpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
- It is recommendable to crash damaged or unnecessary LCD into pieces and washoff liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact withyour hands, please wash it off well with soap and water.



## 11. Outline Dimensions:

